

2SJ526 Silicon P Channel MOS FET

REJ03G0876-0600 Rev.6.00 Jun 05, 2006

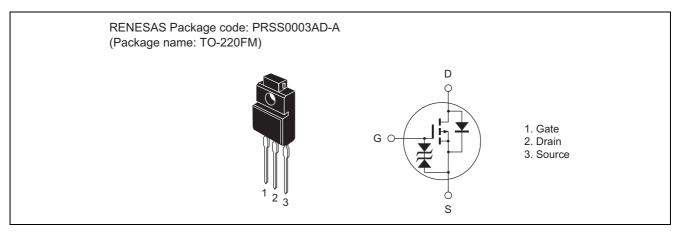
Description

High speed power switching

Features

- Low on-resistance
 - $R_{DS (on)} = 0.11 \ \Omega \ typ.$
- Low drive current
- 4 V gate drive devices
- High speed switching

Outline





Absolute Maximum Ratings

			$(Ta = 25^{\circ}C)$
Item	Symbol	Value	Unit
Drain to source voltage	V _{DSS}	-60	V
Gate to source voltage	V _{GSS}	±20	V
Drain current	ID	-12	A
Drain peak current	I _{D (pulse)} Note 1	-48	A
Body to drain diode reverse drain current	I _{DR}	-12	A
Avalanche current	I _{AP} Note 3	-12	A
Avalanche energy	E _{AR} Note 3	12	mJ
Channel dissipation	Pch Note 2	25	W
Channel temperature	Tch	150	°C
Storage temperature	Tstg	-55 to +150	٦°

Notes: 1. $PW \le 10 \ \mu s$, duty cycle $\le 1\%$

2. Value at $Tc = 25^{\circ}C$

3. Value at Tch = 25° C, Rg $\geq 50 \Omega$

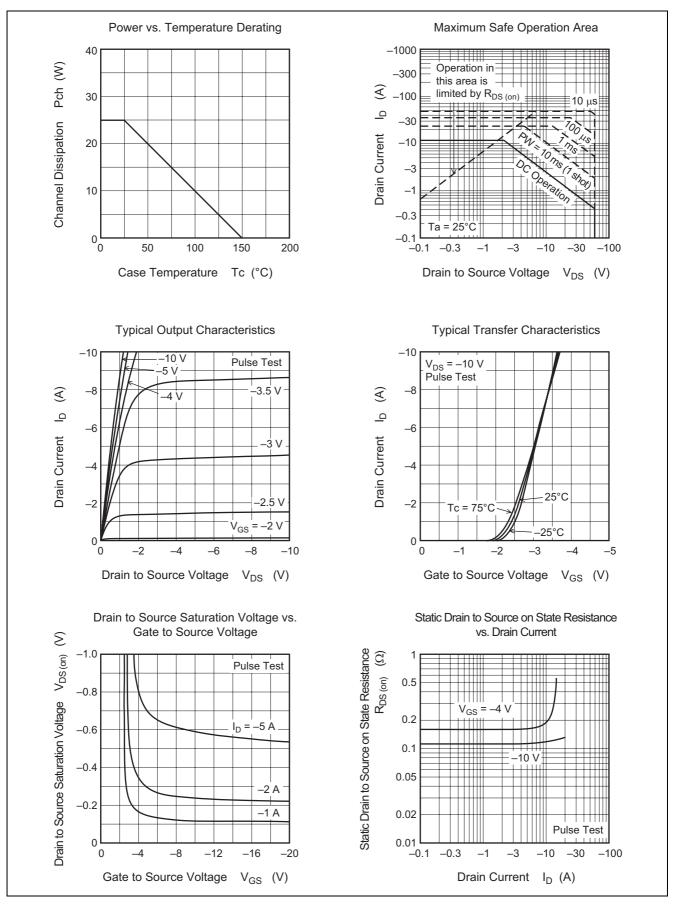
Electrical Characteristics

						$(Ta = 25^{\circ}C)$
Item	Symbol	Min	Тур	Max	Unit	Test Conditions
Drain to source breakdown voltage	V (BR) DSS	-60			V	$I_D = -10 \text{ mA}, V_{GS} = 0$
Gate to source breakdown voltage	V (BR) GSS	±20	—		V	$I_{G} = \pm 100 \ \mu A, \ V_{DS} = 0$
Zero gate voltage drain current	I _{DSS}	—	—	-10	μΑ	$V_{DS} = -60 \text{ V}, \text{ V}_{GS} = 0$
Gate to source leak current	I _{GSS}	—	—	±10	μΑ	$V_{GS} = \pm 16 \text{ V}, \text{ V}_{DS} = 0$
Gate to source cutoff voltage	V _{GS (off)}	-1.0	—	-2.0	V	$I_D = -1 \text{ mA}, V_{DS} = -10 \text{ V}$
Static drain to source on state resistance	R _{DS (on)}	_	0.11	0.15	Ω	$I_D = -6 \text{ A}, V_{GS} = -10 \text{ V}^{\text{Note 4}}$
	R _{DS (on)}	_	0.16	0.23	Ω	$I_D = -6 A, V_{GS} = -4 V^{Note 4}$
Forward transfer admittance	y _{fs}	5	8		S	$I_D = -6 \text{ A}, V_{DS} = -10 \text{ V}^{\text{Note 4}}$
Input capacitance	Ciss	_	580		pF	$V_{DS} = -10 \text{ V}$
Output capacitance	Coss	_	300		pF	$V_{GS} = 0$
Reverse transfer capacitance	Crss		85		pF	f = 1 MHz
Turn-on delay time	t _{d (on)}	_	10		ns	$V_{GS} = -10 \text{ V}$
Rise time	tr	_	55	_	ns	I _D = -6 A
Turn-off delay time	t _{d (off)}		85		ns	$R_L = 5 \Omega$
Fall time	t _f		60		ns	
Body to drain diode forward voltage	V _{DF}		-1.2		V	$I_F = -12 \text{ A}, V_{GS} = 0$
Body to drain diode reverse recovery time	t _{rr}		60		ns	$I_F = -12 \text{ A}, V_{GS} = 0$
						di _F /dt = 50 A/µs

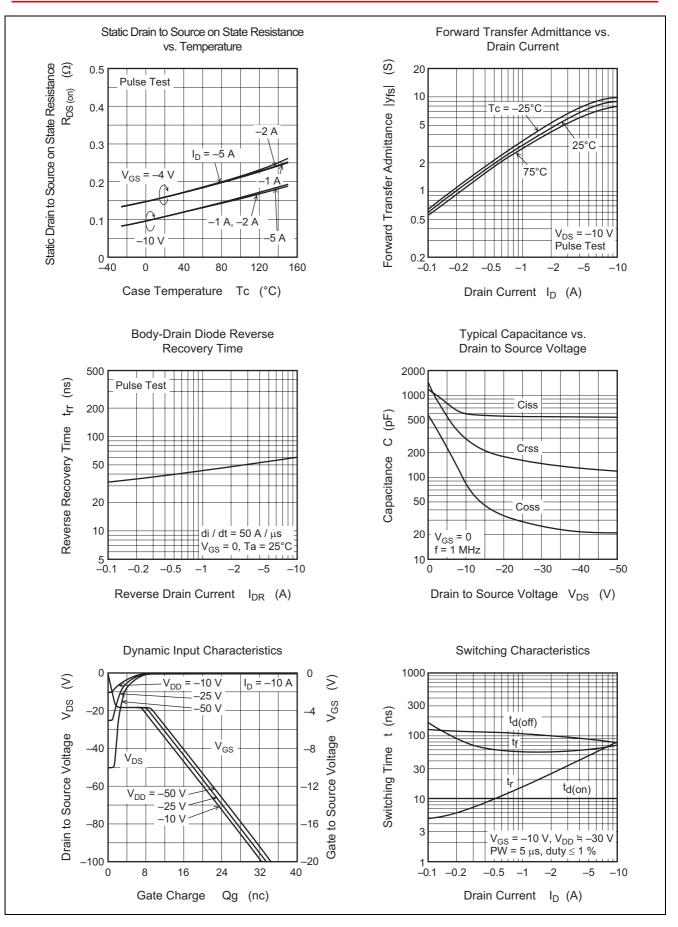
Note: 4. Pulse test



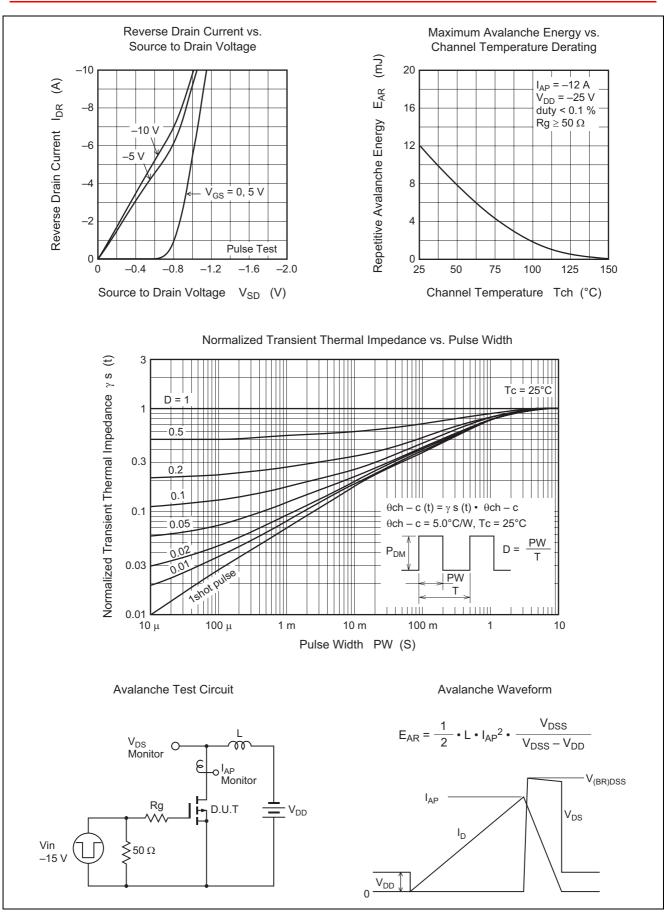
Main Characteristics



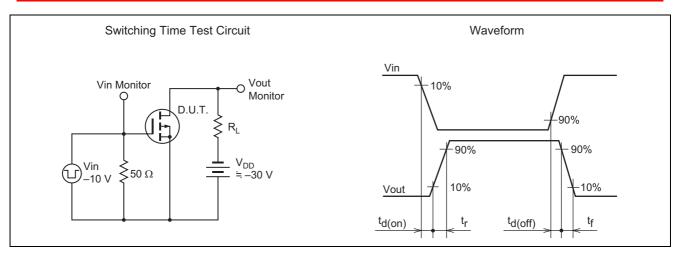






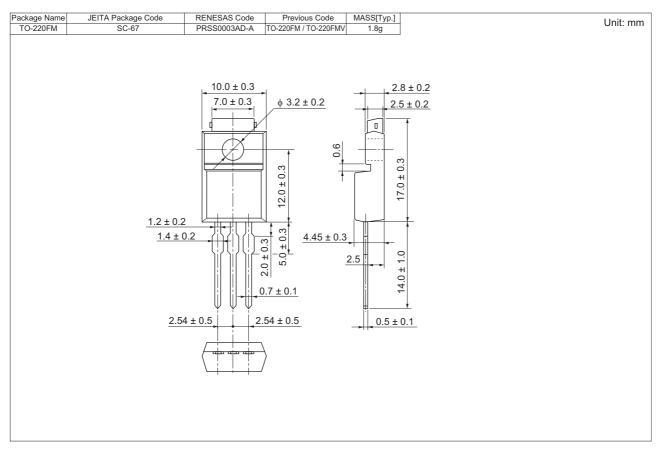








Package Dimensions



Ordering Information

Part Name	Quantity	Shipping Container
2SJ526-E	500 pcs	Box (Sack)

Note: For some grades, production may be terminated. Please contact the Renesas sales office to check the state of production before ordering the product.



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